

Fig. 11 a Power dissipation per diode vs. forward current and ambient temperature

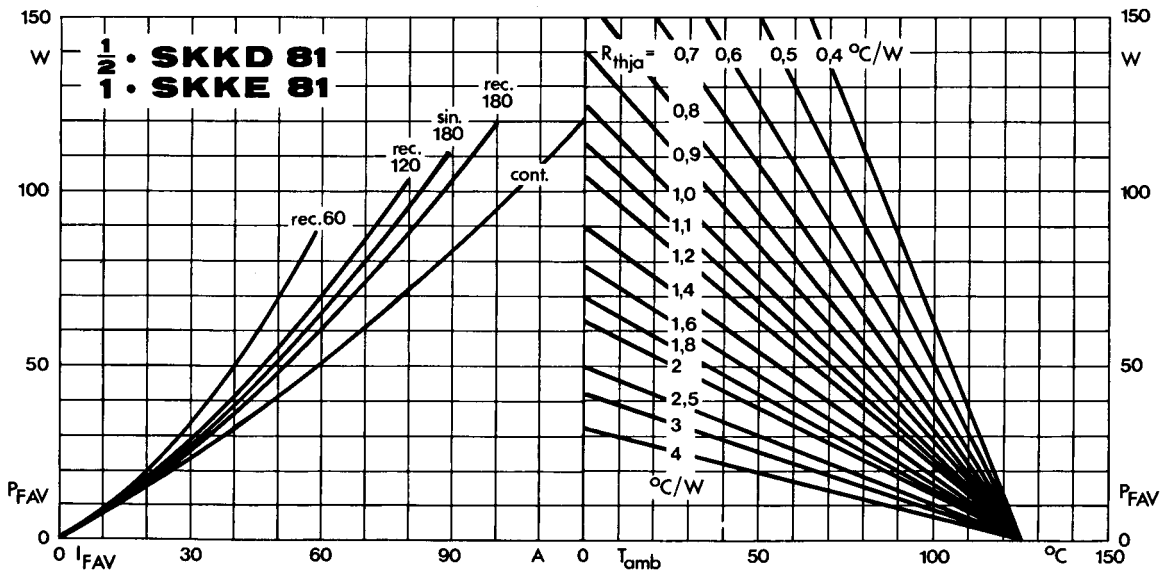


Fig. 11 b Power dissipation per diode vs. forward current and ambient temperature

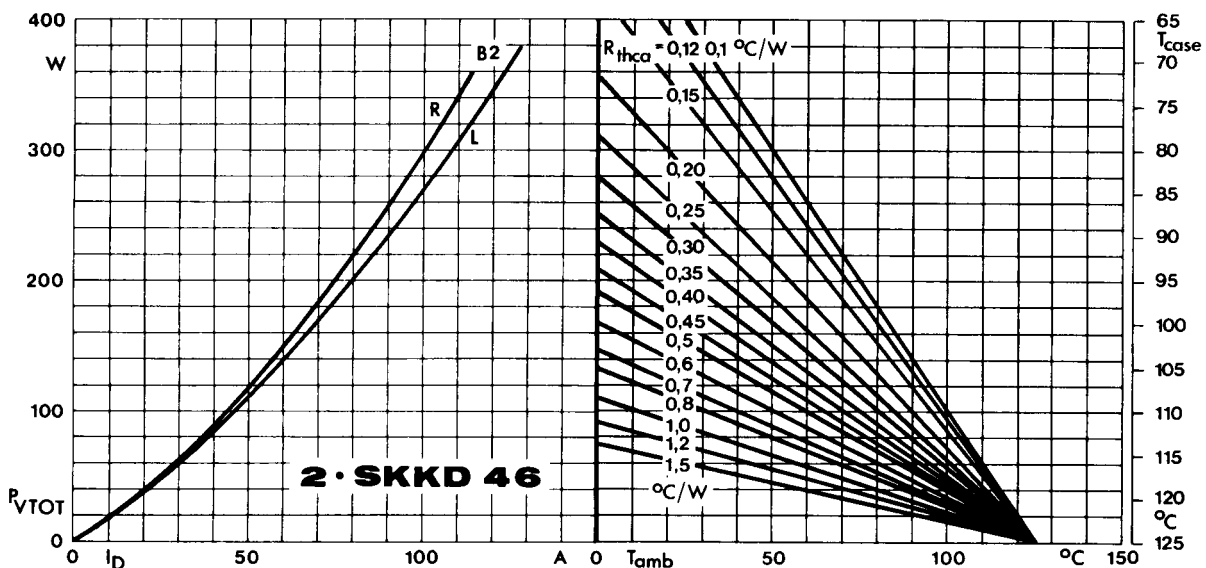


Fig. 12 a Power dissipation of two modules vs. direct current and case temperature

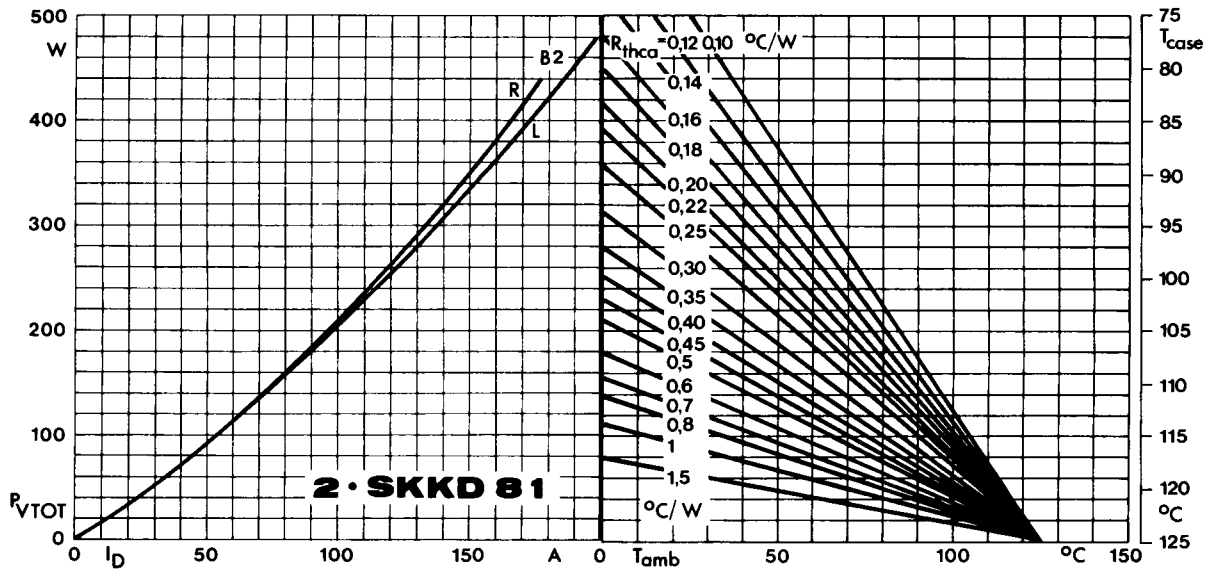


Fig. 12 b Power dissipation of two modules vs. direct current and case temperature

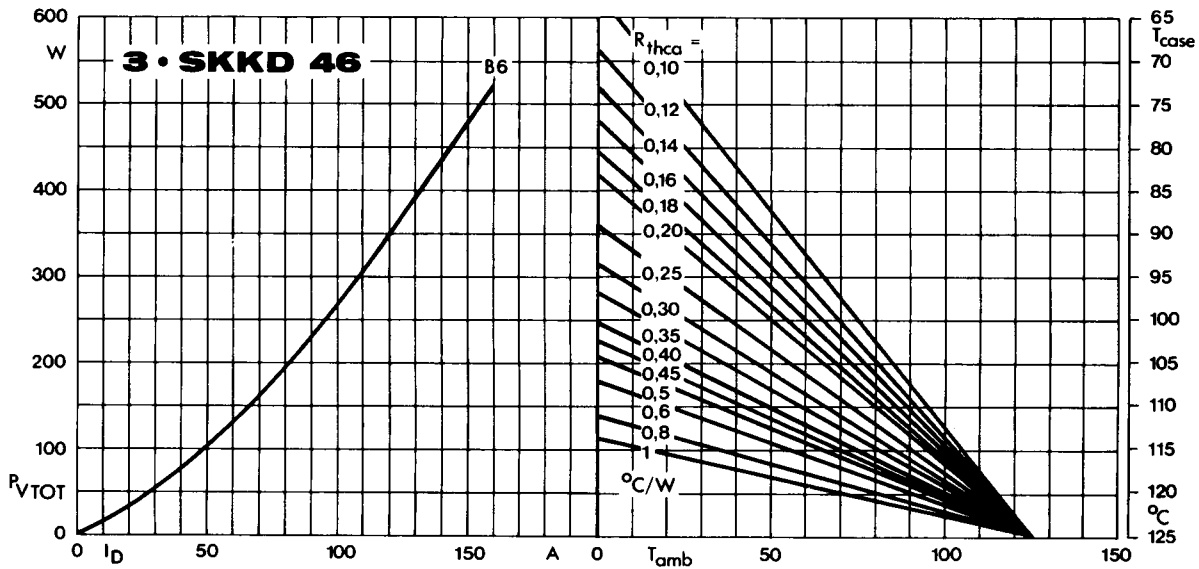


Fig. 13 a Power dissipation of three modules vs. direct current and case temperature

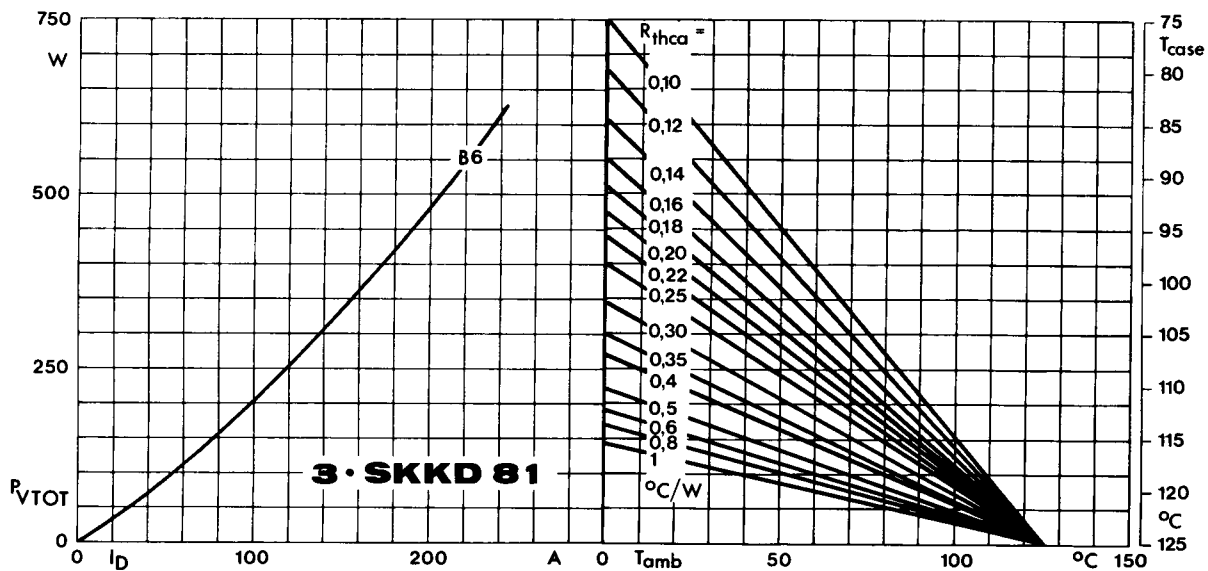


Fig. 13 b Power dissipation of three modules vs. direct current and case temperature

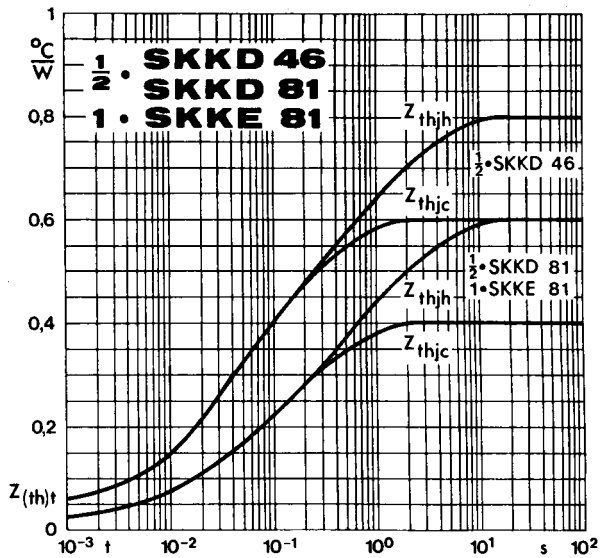


Fig. 14 Transient thermal impedance vs. time

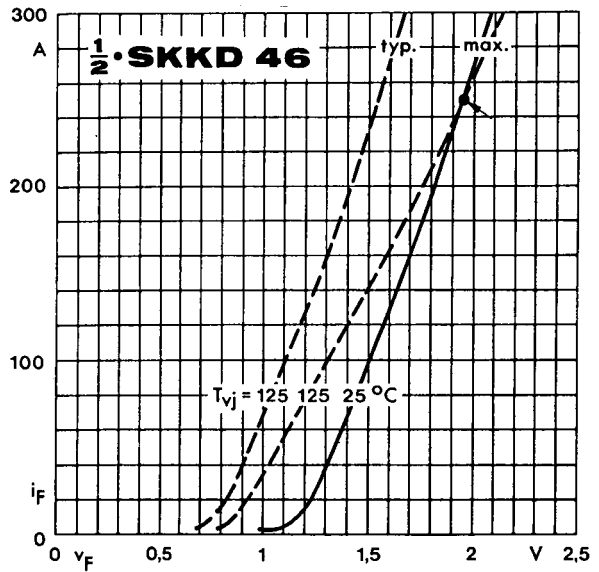


Fig. 15 a Forward characteristics

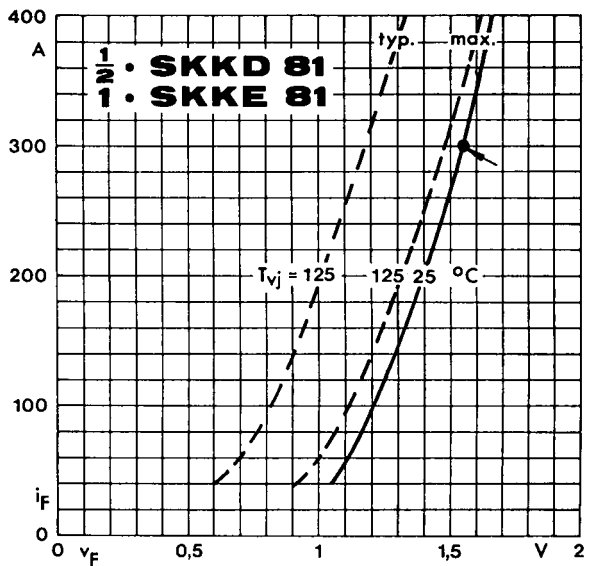


Fig. 15 b Forward characteristics

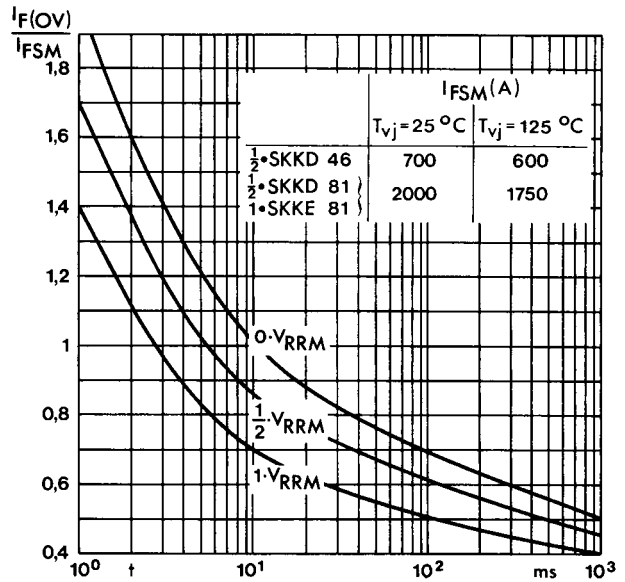


Fig. 16 Surge overload current vs. time

## SKKT 19 ... 105

Case A 5

IEC 192-2: A 77 A

JEDEC: TO-240 AA

SEMIPACK® 1

UL recognized, file no. E 63 532



Dimensions in mm

## SKKT 20/ ... 106/

Case A 46

IEC 192-2: A 77 A

JEDEC: TO-240 AA

SEMIPACK® 1



Dimensions in mm

## SKKH 26 ... 105

Case A 6



## SKKD 26 ... 100

Case A 10



## SKNH 56 ... 91

Case A 7



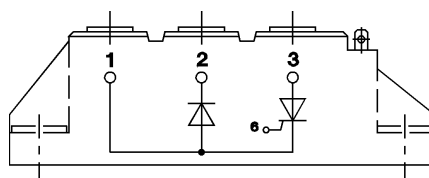
## SKKE 81

Case A 12



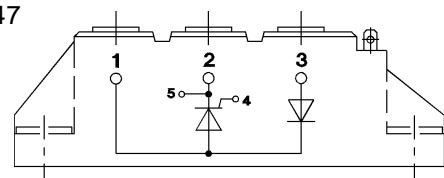
## SKKL 56 ... 105

Case A 9



## SKKH 27 ... 106

Case A 47



## SKND 46 ... 81

Case A 19



## SKKT 20 B ... 106 B

Case A 48



## SKMT 92

Case A 72



## SKKL 42 ... 106

Case A 59

